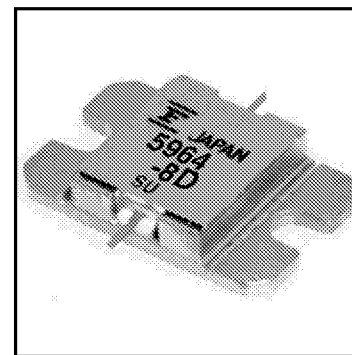


### FEATURES

- High Output Power:  $P_{1dB} = 39.0\text{dBm}$  (Typ.)
- High Gain:  $G_{1dB} = 8.0\text{dB}$  (Typ.)
- High PAE:  $\eta_{add} = 30\%$  (Typ.)
- Low  $IM_3 = -45\text{dBc}@P_o = 28\text{dBm}$
- Broad Band: 5.9 ~ 6.4GHz
- Impedance Matched  $Z_{in}/Z_{out} = 50\Omega$
- Hermetically Sealed Package



### DESCRIPTION

The FLM5964-8D is a power GaAs FET that is internally matched for standard communication bands to provide optimum power and gain in a 50 ohm system.

Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.

### ABSOLUTE MAXIMUM RATING (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Condition	Rating	Unit
Drain-Source Voltage	$V_{DS}$		15	V
Gate-Source Voltage	$V_{GS}$		-5	V
Total Power Dissipation	$P_T$	$T_C = 25^\circ\text{C}$	42.8	W
Storage Temperature	$T_{stg}$		-65 to +175	$^\circ\text{C}$
Channel Temperature	$T_{ch}$		175	$^\circ\text{C}$

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

1. The drain-source operating voltage ( $V_{DS}$ ) should not exceed 10 volts.
2. The forward and reverse gate currents should not exceed 16.0 and -4.4 mA respectively with gate resistance of 100 $\Omega$ .

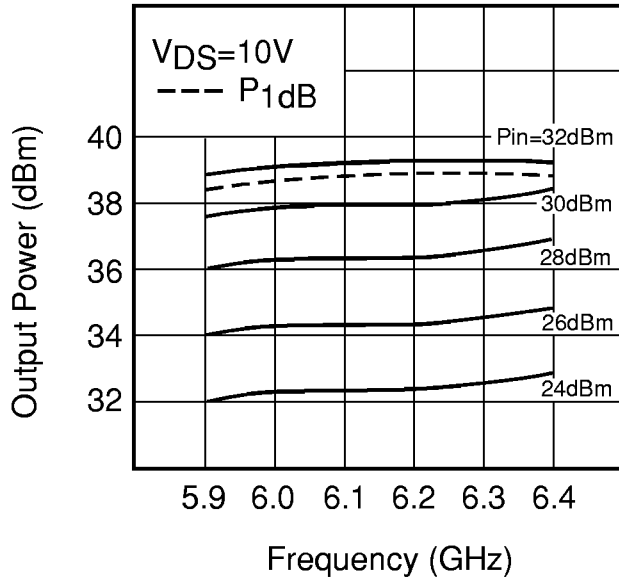
### ELECTRICAL CHARACTERISTICS (Ambient Temperature $T_a=25^\circ\text{C}$ )

Item	Symbol	Test Conditions	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	$I_{DSS}$	$V_{DS} = 5\text{V}, V_{GS} = 0\text{V}$	-	3600	5400	mA
Transconductance	$g_m$	$V_{DS} = 5\text{V}, I_{DS} = 2200\text{mA}$	-	2000	-	mS
Pinch-off Voltage	$V_p$	$V_{DS} = 5\text{V}, I_{DS} = 180\text{mA}$	-1.0	-2.0	-3.5	V
Gate Source Breakdown Voltage	$V_{GSO}$	$I_{GS} = -180\mu\text{A}$	-5	-	-	V
Output Power at 1dB G.C.P.	$P_{1dB}$	$V_{DS} = 10\text{V},$ $I_{DS} = 0.55 I_{DSS}$ (Typ.), $f = 5.9 \sim 6.4 \text{GHz},$ $Z_S = Z_L = 50 \text{ohm}$	38	39	-	dBm
Power Gain at 1dB G.C.P.	$G_{1dB}$		7.0	8.0	-	dB
Drain Current	$I_{dsr}$		-	2200	2600	mA
Power-added Efficiency	$\eta_{add}$		-	30	-	%
Gain Flatness	$\Delta G$		-	-	$\pm 0.6$	dB
3rd Order Intermodulation Distortion	$IM_3$	$f = 6.4 \text{GHz}, \Delta f = 10 \text{MHz}$ 2-Tone Test $P_{out} = 28\text{dBm S.C.L.}$	-42	-45	-	dBc
Thermal Resistance	$R_{th}$	Channel to Case	-	3.0	3.5	$^\circ\text{C/W}$

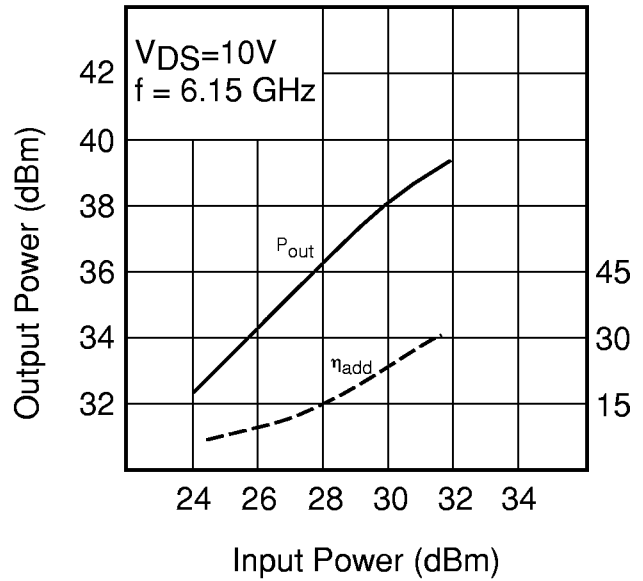
CASE STYLE: IB

G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level

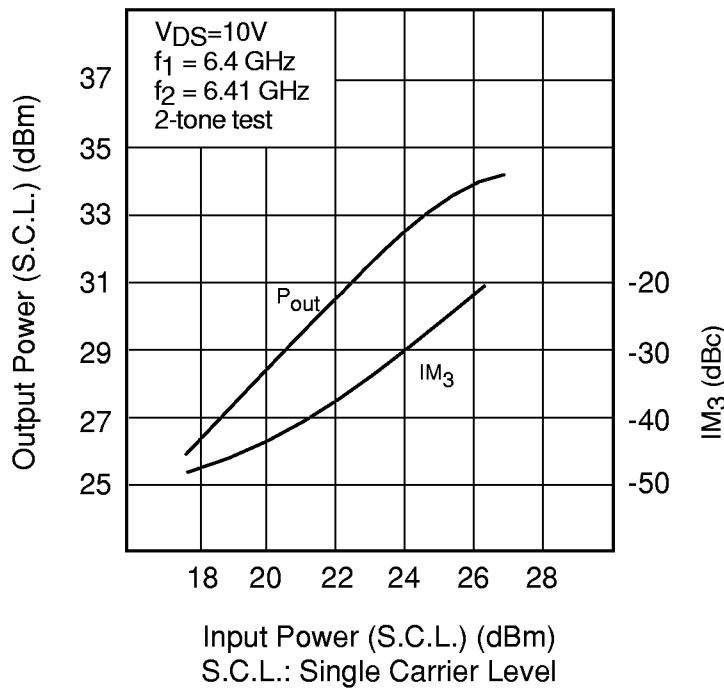
**OUTPUT POWER vs. FREQUENCY**



**OUTPUT POWER vs. INPUT POWER**

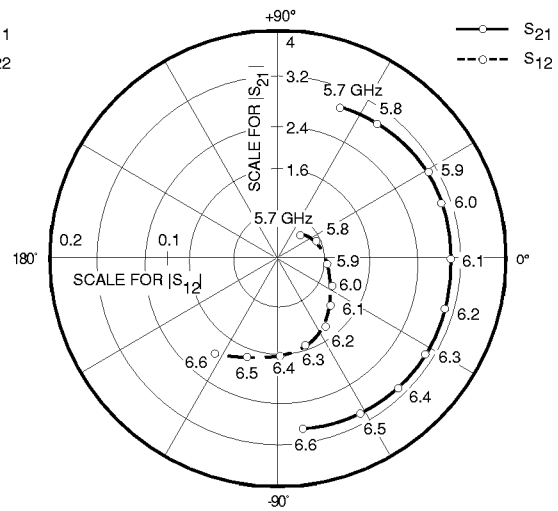
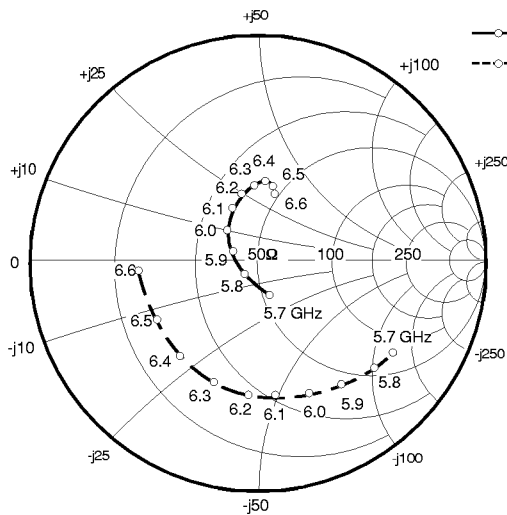


**OUTPUT POWER & IM<sub>3</sub> vs. INPUT POWER**



# FLM5964-8D

## Internally Matched Power GaAs FETs



### S-PARAMETERS

$V_{DS} = 10V, I_{DS} = 2200mA$

FREQUENCY (MHZ)	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5800	.08	-131	2.85	50	.03	20	.69	-41
5900	.12	163	2.87	30	.04	-5	.65	-54
6000	.19	133	2.97	16	.05	-22	.62	-66
6100	.25	116	2.99	0	.05	-40	.59	-82
6200	.30	104	3.00	-14	.06	-58	.57	-96
6300	.33	92	2.99	-31	.07	-74	.54	-112
6400	.33	84	3.01	-46	.08	-89	.53	-133
6500	.32	77	3.02	-61	.08	-105	.54	-152
6600	.29	73	2.92	-80	.09	-122	.54	-174

**Case Style "IB"**  
Metal-Ceramic Hermetic Package

